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- Internal Look-Ahead Circuitry for Fast Counting
- Carry Output for N-Bit Cascading
- Fully Synchronous Operation for Counting

description

This synchronous, presettable, 4-bit binary counter has internal carry look-ahead circuitry for use in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when

D, DB, OR N PACKAGE (TOP VIEW)										
CLR CLK A B C C C C C C C D C SND	1 2 3 4 5 6 7 8	16 15 14 13 12 11 10 9	V _{CC} RCO Q _A Q _B Q _C Q _D ENT LOAD							

so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that are normally associated with asynchronous (ripple-clock) counters. However, counting spikes can occur on the ripple-carry (RCO) output. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of CLK.

This counter is fully programmable. That is, it can be preset to any number between 0 and 15. Because presetting is synchronous, a low logic level at the load (\overline{LOAD}) input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of ENP and ENT.

The clear function is asynchronous, and a low logic level at the clear (CLR) input sets all four of the flip-flop outputs to low, regardless of the levels of CLK, LOAD, ENP, and ENT.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications, without additional gating. This function is implemented by the ENP and ENT inputs and an RCO output. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. RCO, thus enabled, produces a high-logic-level pulse while the count is 15 (HHHH). The high-logic-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

The SN74F161A features a fully independent clock circuit. Changes at ENP, ENT, or LOAD that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the setup and hold times.

TA	PACKA	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
F	PDIP – N	Tube	SN74F161AN	SN74F161AN		
0°C to 70°C	SOIC - D	Tube	SN74F161AD	F161A		
0010700	30IC - D	Tape and reel	SN74F161ADR	FIOTA		
	SSOP – DB	Tape and reel	SN74F161ADBR	F161A		

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



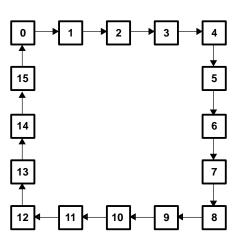
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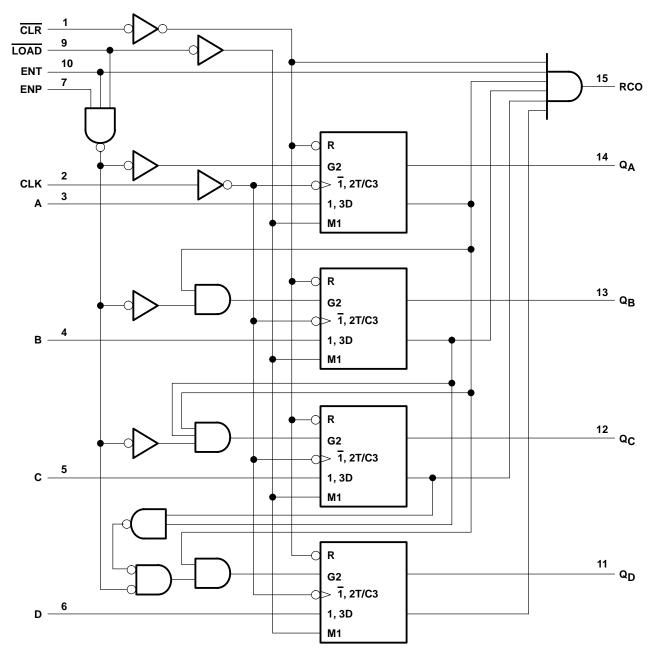
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state diagram





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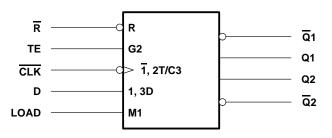


logic diagram (positive logic)

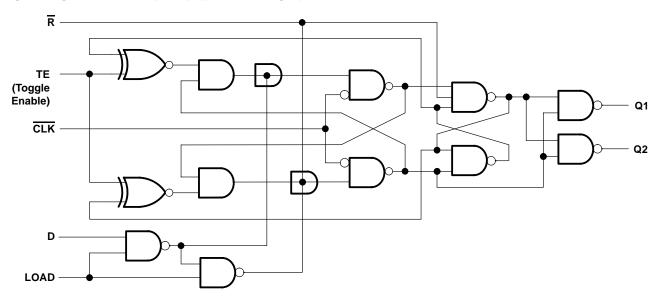


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logic symbol, each flip-flop



logic diagram, each flip-flop (positive logic)



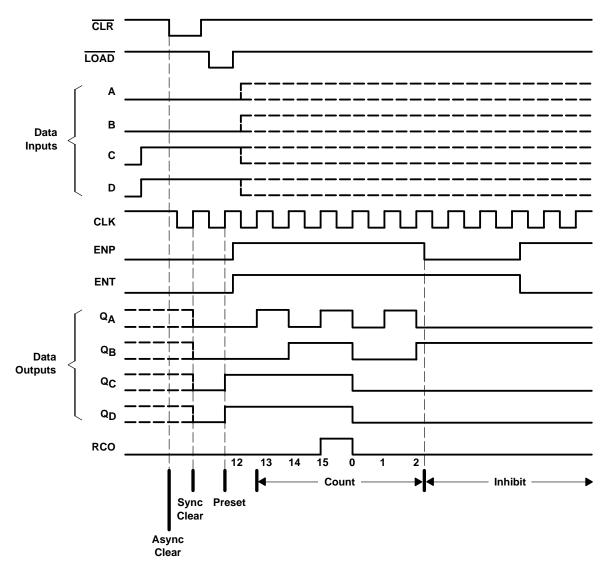


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typical clear, preset, count, and inhibit sequences

The following timing sequence is illustrated below:

- 1. Clear outputs to zero
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Input voltage range, V_I (see Note 1) -1.2 V to 7 Input current range -30 mA to 5 m Voltage range applied to any output in the high state -0.5 V to V_C Current into any output in the low state 40 m Package thermal impedance, θ_{JA} (see Note 2): D package 73°C/ DB package 82°C/ N package 67°C	nA CC nA ′W ′W
/N package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input voltage ratings may be exceeded provided the input current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
Iк	Input clamp current			-18	mA
ЮН	High-level output current			-1	mA
IOL	Low-level output current			20	mA
Т _А	Operating free-air temperature	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TE	TEST CONDITIONS				
VIK		V _{CC} = 4.5 V,	l _l = –18 mA			-1.2	V
V _{OH}		$V_{CC} = 4.5 V,$	I _{OH} = – 1 mA	2.5	3.4		V
		V _{CC} = 4.75 V,	I _{OH} = – 1 mA	2.7			v
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 20 mA		0.3	0.5	V
Ц		V _{CC} = 5.5 V,	V _I = 7 V			0.1	mA
Iн		V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA
	ENP, CLK, A, B, C, D					- 0.6	
۱ _{۱L}	ENT, LOAD	V _{CC} = 5.5 V,	V _I = 0.5 V			- 1.2	mA
	CLR					- 0.6	
los§		V _{CC} = 5.5 V,	$V_{O} = 0$	-60		-150	mA
ICC		V _{CC} = 5.5 V			37	55	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				V _{CC} = T _A = 2	= 5 V, 25°C	MIN	МАХ	UNIT		
				MIN	MAX					
fclock	Clock frequency			0	100	0	90	MHz		
		CLK high or low (loading)		5		5				
+	Pulse duration	CLK (counting)	High	4		4		nc		
tw	W T dioc dalation	CER (counting)	Low	6		7		ns		
		CLR low	CLR low							
		Data before CLK [↑]	High or low	5		5				
		LOAD before CLK	High	11		11.5				
t _{su}	Setup time	LOAD before CLK	Low	8.5		9.5		ns		
		ENP and ENT before CLK	High	11		11.5				
		ENF and ENT Delote CERT	Low	5		5				
		Data after CLK [↑]	High or low	2		2				
+ .	Hold time		High	2		2				
^t h	h Hold time	LOAD after CLK [↑]	Low	0		0		ns		
		ENP and ENT after CLK [↑] High or low				0				
t _{su}	Inactive-state setup time, C	6		6		ns				

[†] Inactive-state setup time also is referred to as recovery time.

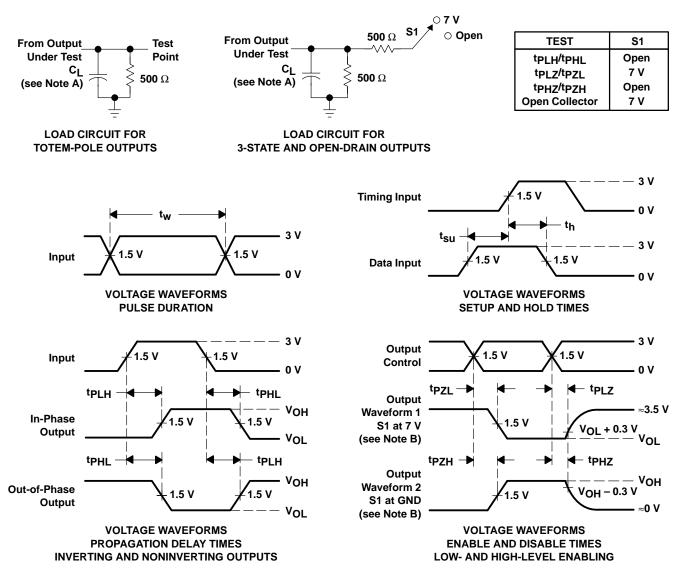
switching characteristics (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL RL	CC = 5 V = 50 Pl = 500 Ω = 500 Ω	F, 2,	V _{CC} = 4.5 V C _L = 50 R _L = 50 T _A = MIN TC	UNIT		
			MIN	TYP	MAX	MIN	MAX		
fmax			100	120		90		MHz	
^t PLH	CLK (LOAD high)	Amu 0	2.7	5.1	7.5	2.7	8.5	ns	
^t PHL	CLK (LOAD high)	Any Q	2.7	7.1	10	2.7	11	115	
^t PLH	CLK (LOAD low)	Amu 0	3.2	5.6	8.5	3.2	9.5	ns	
^t PHL	CLK (LOAD IOW)	Any Q	3.2	5.6	8.5	3.2	9.5	115	
^t PLH	CLK	RCO	4.2	9.6	14	4.2	15	ns	
^t PHL	OLK	RCO	4.2	9.6	14	4.2	15	115	
^t PLH		DCO.	1.7	4.1	7.5	1.7	8.5	ns	
^t PHL	ENT	RCO	1.7	4.1	7.5	1.7	8.5	115	
t-		Any Q	4.7	8.6	12	4.7	13		
^t PHL	CLR	RCO	3.7	7.6	10.5	3.7	11.5	ns	

[‡] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 4: Load circuits and waveforms are shown in Figure 1.



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns, duty cycle = 50%.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74F161AD	LIFEBUY	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F161A	
SN74F161ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	F161A	Samples
SN74F161AN	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74F161AN	Samples
SN74F161ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F161A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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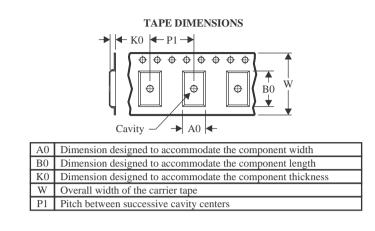


Texas

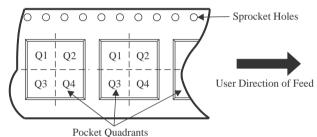
STRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



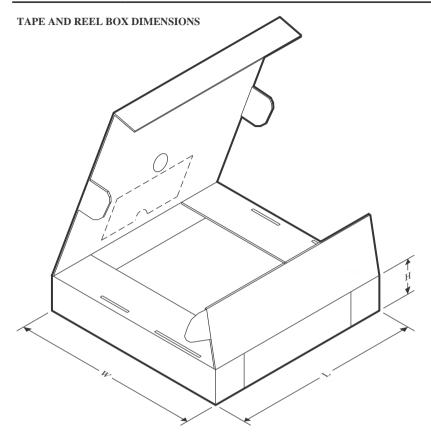
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F161ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74F161ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

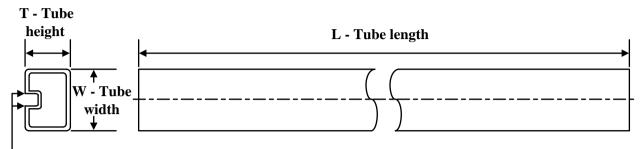
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F161ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74F161ANSR	SO	NS	16	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74F161AD	D	SOIC	16	40	507	8	3940	4.32
SN74F161AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74F161AN	N	PDIP	16	25	506	13.97	11230	4.32

NS0016A



PACKAGE OUTLINE

SOP - 2.00 mm max height

SOP



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



NS0016A

EXAMPLE BOARD LAYOUT

SOP - 2.00 mm max height

SOP



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



NS0016A

EXAMPLE STENCIL DESIGN

SOP - 2.00 mm max height

SOP



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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